



Session Title:	[TC3] CMP Innovations
Session Date:	November 21 (Tue.), 2023
Session Time:	14:25-16:00
Session Room:	Room C (Grand Ballroom 2, 2F)
Session Chair:	Prof. Sangwoo Lim (Yonsei Univ., Korea)

[TC3-1] [Invited] 14:25-14:55

Enhancing Advanced Memory Development through CMP Innovations

Hyo-Chol Koo, Hyun Min Lee, and Byoungki Lee (SK hynix, Korea)

[TC3-2] 14:55-15:15

1-Step Tungsten Chemical-Mechanical Planarization Performing Remarkable High Tungsten Film Polishing-Rate and Reverse Polishing-Rate Selectivity between Tungsten-And SiO₂-film via Radical Oxidation

Seong-In Kim, Jin-Woong Cho, Seon-Hwa Kang (Hanyang Univ., Korea), Jin-Hyung Park (ENF Tech. Inc., Korea), and Jea-Gun Park (Hanyang Univ., Korea)

[TC3-3] [Plenary] 15:15-16:00

A Holistic Approach to Optimizing Chemical Mechanical Planarization (CMP) for Enhanced Semiconductor Manufacturing and Sustainability

Jihoon Seo (Clarkson Univ., USA)